

IN THE CLAIMS

Please cancel Claims 10-11, 13-15, 17-20 and 33-38 without prejudice or disclaimer.

Please add the following new Claims:

New Claim 43. A semiconductor package in accordance with Claim 39 wherein a first end of the at least one first conductive wire is bonded on the substrate by ball bonding and a second end of the at least one first conductive wire is bonded on the at least one input-output pad of the first semiconductor chip by stitch bonding.

New Claim 44. A semiconductor package in accordance with Claim 43 wherein a conductive ball is formed on the at least one input-output pad of the first semiconductor chip bonded by the stitch bonding.

New Claim 45. A semiconductor package in accordance with Claim 39 wherein a first end of the at least one first conductive wire is bonded on the substrate and a second end of the at least one first conductive wire is bonded on the at least one input-output pad of the first semiconductor chip by stitch bonding.

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cont. New Claim 46. A semiconductor package in accordance with
Claim 45 wherein a first end of the at least one first conductive
wire is bonded on the substrate and a second end of the at least
one first conductive wire is bonded on the at least one input-
output pad of the first semiconductor chip by stitch bonding.



CLEAN VERSION OF NEW CLAIMS

Claim 43. A semiconductor package in accordance with Claim 39 wherein a first end of the at least one first conductive wire is bonded on the substrate by ball bonding and a second end of the at least one first conductive wire is bonded on the at least input-output pad of the first semiconductor chip by stitch bonding.

Claim 44. A semiconductor package in accordance with Claim 43 wherein a conductive ball is formed on the at least one input-output pad of the first semiconductor chip bonded by the stitch bonding.

Claim 45. A semiconductor package in accordance with Claim 39 wherein a first end of the at least one first conductive wire is bonded on the substrate and a second end of the at least one first conductive wire is bonded on the at least one input-output pad of the first semiconductor chip by stitch bonding.

Claim 46. A semiconductor package in accordance with Claim 45 wherein a first end of the at least one first conductive wire is bonded on the substrate and a second end of the at least one first conductive wire is bonded on the at least one input-output pad of the first semiconductor chip by stitch bonding.